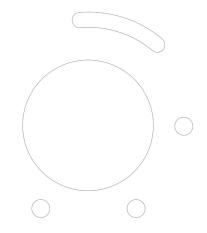


## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01585 REV: E1	SUN REV: Not In VersionControl
	TID #: 01585	
PLOT NAME = Top Assembly Drawing	GENERATED : 2018/3/12 14:32:4	1 TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01585 REV: E1	SUN REV: Not In VersionControl
	TID #: 01585	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2018/3/12 14:32:4	2 TEXAS INSTRUMENTS

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